

APPLICATIONS

- ✓ Cellular Phones
- ✓ MCM Boards
- ✓ Wireless Communication Circuits
- ✓ IR LEDs
- ✓ SMART & PCMCIA Cards

IEC COMPATIBILITY (EN61000-4)

- ✓ 61000-4-2 (ESD): Air - 15kV, Contact - 8kV
- ✓ 61000-4-4 (EFT): 40A - 5/50ns

FEATURES

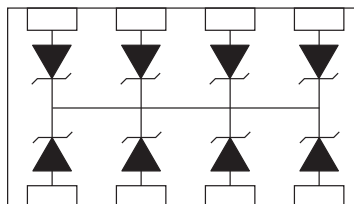
- ✓ ESD Protection > 25 kilovolts
- ✓ Available in Voltages Ranging From 3.3V to 36V
- ✓ 250 Watts Peak Pulse Power per Line ($t_p = 8/20\mu s$)
- ✓ Bidirectional Configuration & Monolithic Structure
- ✓ Protects 4 to 7 Lines
- ✓ RoHS Compliant

MECHANICAL CHARACTERISTICS

- ✓ Standard EIA Chip Size: 0408
- ✓ Weight 0.73 milligrams (Approximate)
- ✓ Available in Lead-Free Plating
- ✓ Solder Reflow Temperature:
 Lead-Free - Sn/Ag/Cu, 96/3.5/0.5: 260-270°C
- ✓ Consult Factory for Leaded Device Availability
- ✓ Flammability Rating UL 94V-0
- ✓ 8mm Plastic & Paper Tape and Reel Per EIA Standard 481
- ✓ Device Marking On Reel
- ✓ Top Contacts: Solder Bump 0.004" in Height (Nominal)



PIN CONFIGURATION



P0408FC3.3C* thru P0408FC36C*

DEVICE CHARACTERISTICS

MAXIMUM RATINGS @ 25°C Unless Otherwise Specified

PARAMETER	SYMBOL	VALUE	UNITS
Peak Pulse Power (tp = 8/20µs) - See Figure 1	P _{PP}	250	Watts
Operating Temperature	T _A	-55 to 150	°C
Storage Temperature	T _{STG}	-55 to 150	°C

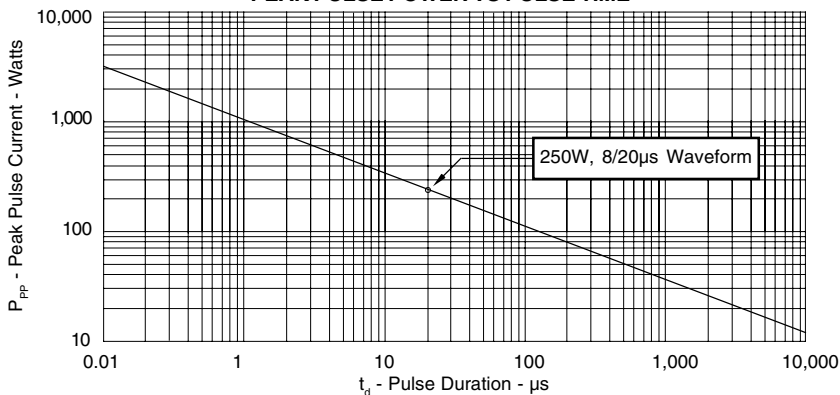
ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified

PART NUMBER (See Note 1)	RATED STAND-OFF VOLTAGE V _{WM} VOLTS	MINIMUM BREAKDOWN VOLTAGE	MAXIMUM CLAMPING VOLTAGE (See Fig. 2)	MAXIMUM CLAMPING VOLTAGE (See Fig. 2)	MAXIMUM LEAKAGE CURRENT (See Note 2)	TYPICAL CAPACITANCE @0V, 1 MHz C pF
		@ 1mA V _(BR) VOLTS	@ I _p = 1A V _C VOLTS	@ 8/20µs V _C @ I _{PP}	@ V _{WM} I _D µA	
P0408FC3.3C	3.3	4.0	7.0	12.5V @ 20A	75*	150
P0408FC05C	5.0	6.0	11.0	14.7V @ 17A	10**	100
P0408FC08C	8.0	8.5	13.2	19.2V @ 13A	10***	75
P0408FC12C	12.0	13.3	19.8	29.7V @ 9.0A	1	50
P0408FC15C	15.0	16.7	25.4	35.7V @ 7.0A	1	40
P0408FC24C	24.0	26.7	37.2	55.0V @ 5.0A	1	30
P0408FC36C	36.0	40.0	70.0	84.0V @ 3.0A	1	25

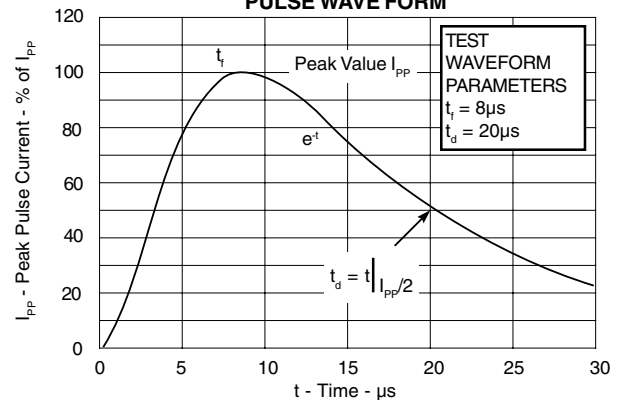
Note 1: All devices are bidirectional. Electrical characteristics apply in both directions.

Note 2: *Maximum leakage current < 5µA @ 2.8V. **Maximum leakage current < 500nA @ 3.3V. ***Maximum leakage current < 200nA @ 5V.

**FIGURE 1
PEAK PULSE POWER VS PULSE TIME**

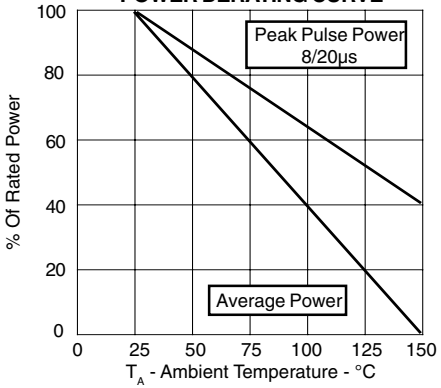


**FIGURE 2
PULSE WAVEFORM**

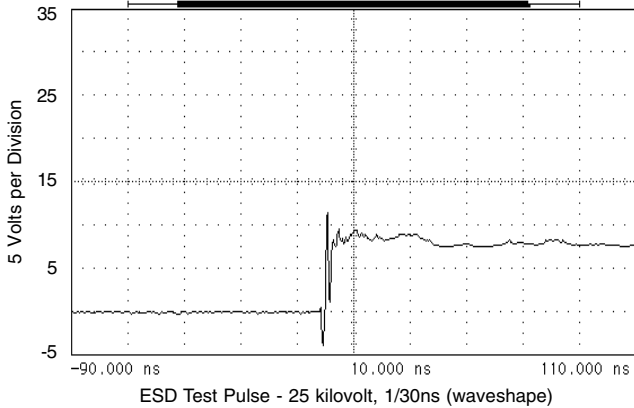


GRAPHS

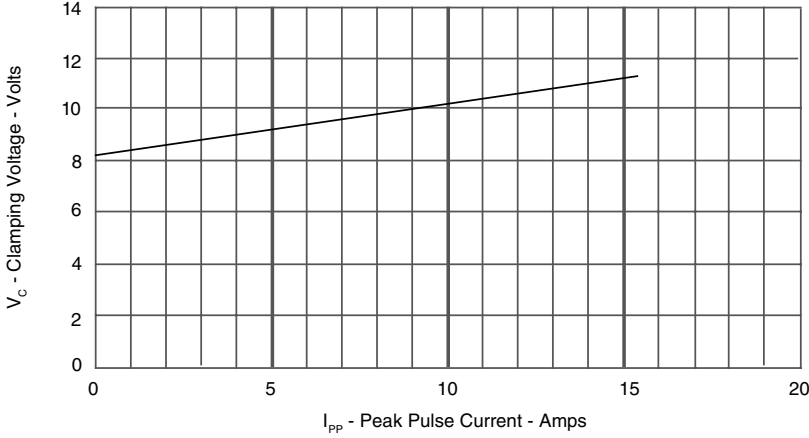
**FIGURE 3
 POWER DERATING CURVE**



**FIGURE 4
 OVERSHOOT & CLAMPING VOLTAGE FOR P0408FC05C**



**FIGURE 5
 TYPICAL CLAMPING VOLTAGE VS PEAK PULSE CURRENT FOR P0408FC05C**

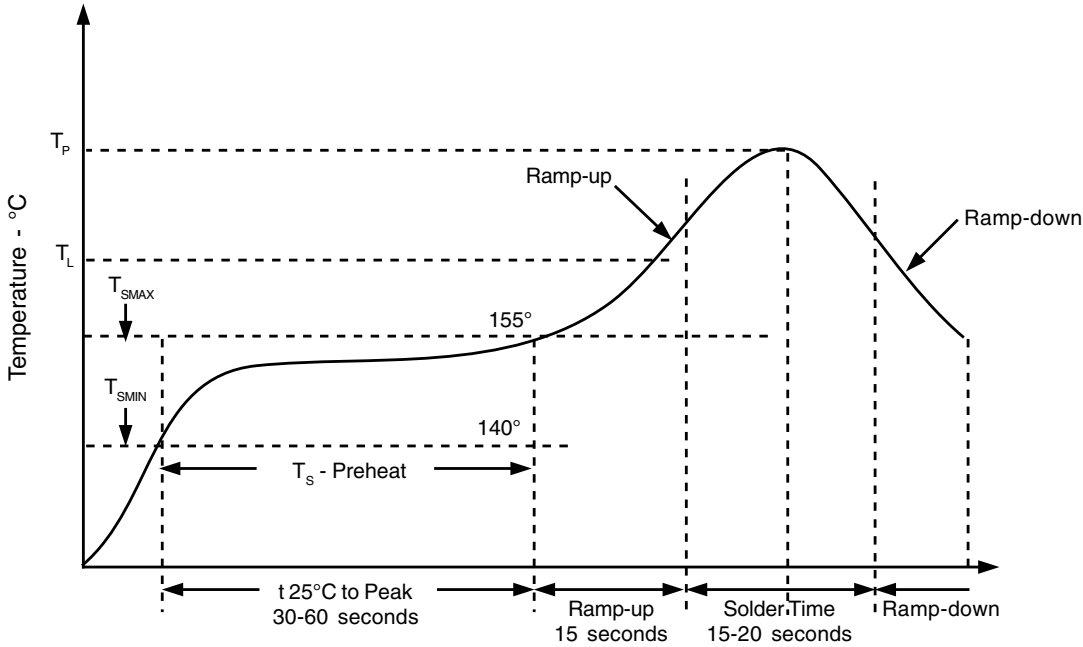
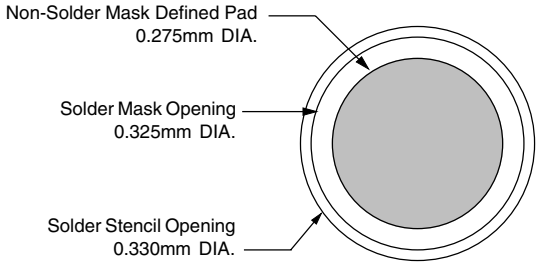


APPLICATION INFORMATION

PRINTED CIRCUIT BOARD RECOMMENDATIONS	
PARAMETER	VALUE
Pad Size on PCB	0.275mm
Pad Shape	Round
Pad Definition	Non-Solder Mask Defined Pads
Solder Mask Opening	0.325mm Round
Solder Stencil Thickness	0.150mm
Solder Stencil Aperture Opening (laser cut, 5% tapered walls)	0.330mm Round
Solder Paste Type	No Clean
Pad Protective Finish	OSP (Entek Cu Plus 106A)
Tolerance - Edge To Corner Ball	±50µm
Solder Ball Side Coplanarity	±20µm
Maximum Dwell Time Above Liquidous (183°C)	60 Seconds
Soldering Maximum Temperature	270°C

REQUIREMENTS
<p>Temperature:</p> <p>T_p for Lead-Free (SnAgCu): 260-270°C</p> <p>T_p for Tin-Lead: 240-245°C</p> <p>Preheat time and temperature depends on solder paste and flux activation temperature, component size, weight, surface area & plating.</p>

RECOMMENDED NON-SOLDER MASK DEFINED PAD ILLUSTRATION



P0408FC3.3C* thru P0408FC36C*

0408 PACKAGE OUTLINE & DIMENSIONS

PACKAGE OUTLINE

PACKAGE DIMENSIONS

DIM	MILLIMETERS	INCHES
A	0.56 NOM	0.022 NOM
B	0.86 NOM	0.034 NOM
C	0.99 ± 0.0254	0.039 ± 0.001
E	0.15 SQ	0.006 SQ
F	2.0 ± 0.0254	0.079 ± 0.001
G	0.15 NOM	0.006 NOM
H	0.127 MAX	0.005 MAX
I	0.076 MIN	0.003 MIN
I	0.406 NOM	0.016 NOM

NOTES:

- Controlling dimensions in inches.
- Decimal tolerances for mounting pad and outline: .xxx ± 0.05mm (± 0.002").

MOUNTING PAD LAYOUT - Option 1

PAD DIMENSIONS

DIM	MILLIMETERS	INCHES
A	0.51	0.020
C	0.30	0.012
D	0.46	0.018
E	0.20	0.008
F	0.15 SQ	0.006 SQ
G	0.71	0.028
H	0.99	0.039
I	0.51	0.020

NOTE:

- Preferred:* Using 0.1mm (0.004") stencil.

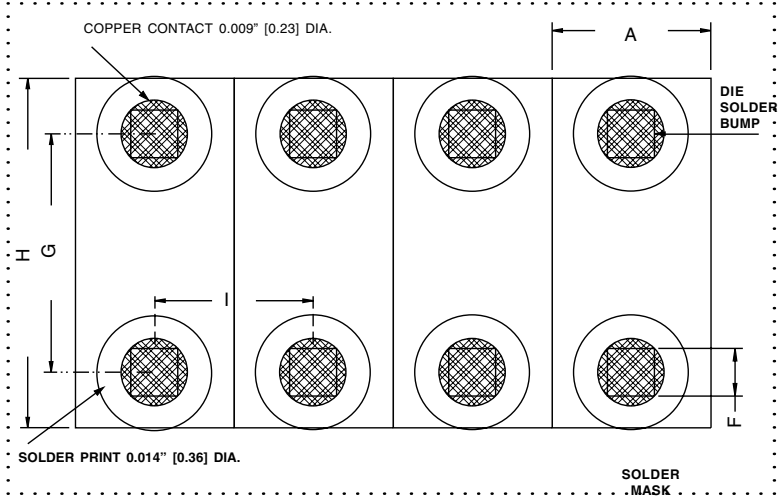
P0408FC3.3C*

thru

P0408FC36C*

0408 PACKAGE OUTLINE & DIMENSIONS

MOUNTING PAD LAYOUT - Option 2

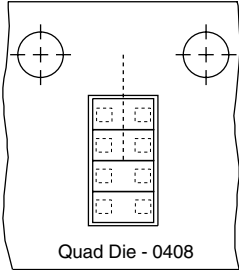


PACKAGE DIMENSIONS

DIM	MILLIMETERS	INCHES
A	0.51	0.020
F	0.15 SQ	0.006 SQ
G	0.71	0.028
H	0.99	0.039
I	0.51	0.020

- NOTES:**
- Controlling dimensions in inches.
 - Decimal tolerances for mounting pad and outline: .xxx ± 0.05mm (± 0.002").
 - Preferred: Using 0.1mm (0.004") stencil.

TAPE & REEL ORIENTATION



- NOTE:**
- Top view of tape. Solder bumps are face down in tape package.

TAPE & REEL ORDERING NOMENCLATURE

- Surface mount product is taped and reeled in accordance with EIA 481.
- 8mm Plastic Tape: 7 Inch Reels - 5,000 pieces per reel. Ordering Suffix: -T75-1, i.e., P0408FC05C-T75-1.
- 8mm Paper Tape: 7 Inch Reels - 5,000 pieces per reel. Ordering Suffix: -T75-2, i.e., P0408FC05C-T75-2.
- Suffix - LF = Lead-Free, i.e., P0408FC05C-LF-T75-1.

Outline & Dimensions: Rev 4 - 2/04, 06021

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